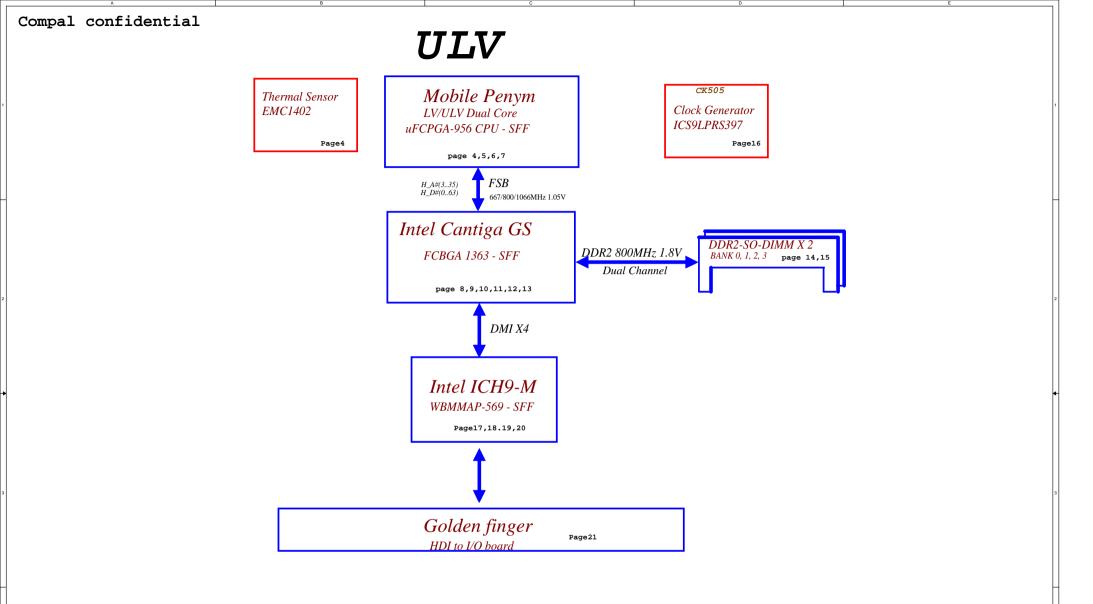
Compal confidential

Schematics Document
Mobile Penryn uFCPGA with Intel
Cantiga_GM+ICH9-M SFF core logic

ULV core logic board

2009/06/23

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A31:

CPU-->SA000038J1L(S IC AV80585VG0091M SLGAM R0 1.2G FCBGA 956P)

CPU-->SA00003BX1L(S IC A31 AV80585UG0132M QLKK R0 1.3G)

NB-->SA00002RQ0L(S IC AC82GS45 SLB92 B3 FCBGA 1363 A31 !)

SB-->SA00001YC3L(S IC AM82801IUX SLB8N A FCBGA ICH9M A31!)

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Voltage Rails (O MEANS ON X MEANS OFF)

power plane	+B	+5VALW +3VALW VL	+1.8V	+5VS +3VS +1.5VS +0.9V +VCCP +CPU_CORE
so	0	0	0	0
s1	0	0	0	0
s3	0	0	0	X
S5 S4/AC	0	0	X	X
S5 S4/ Battery only	0	x	x	X
S5 S4/AC & Battery don't exist	X	X	X	х

I2C / SMBUS ADDRESSING

DEVICE	HEX	ADDRESS
DDR SO-DIMM 0	A0	10100000
CLOCK GENERATOR (EXT.)	D2	11010010

Symbol Note:

: means Digital Ground

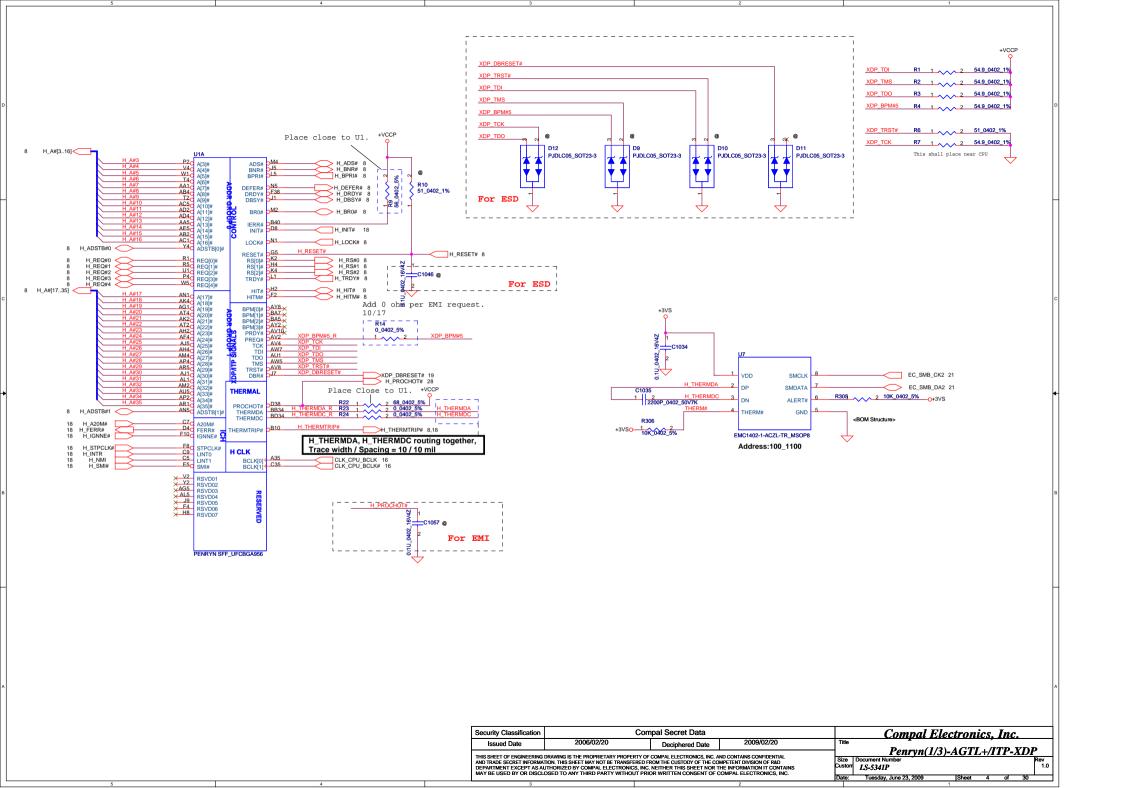
: means Analog Ground

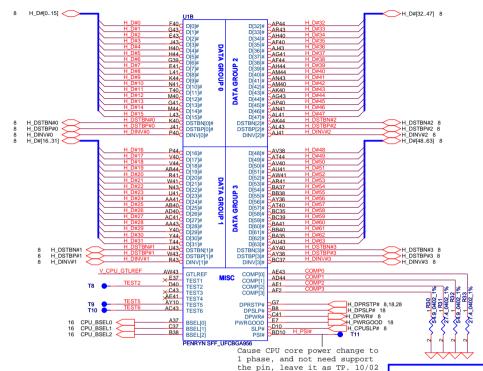
@:means just reserve, no build CONN@:means ME part. 45@:means install after SMT.

SMBUS Control Table

	SOURCE	INVERTER	BATT	SERIAL EEPROM	THERMAL SENSOR (CPU)	SODIMM	CLK CHIP	MINI CARD	LCD
SMB_EC_CK1 SMB_EC_DA1	KB926	X	V	V	X	X	X	X	X
SMB_EC_CK2 SMB_EC_DA2	КВ926	X	X	Х	V	X	X	X	X
SMB_CK_CLK1 SMB_CK_DAT1	ICH9	X	X	X	X	٧	v	v	Х
LCD_CLK LCD_DAT	Cantiga	X	X	Х	Х	X	X	X	v

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Resistor placed within

0.5" of CPU pin.Trace

should be at least 25

toggling signal.

width is 4 mils.

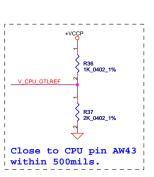
mils away from any other

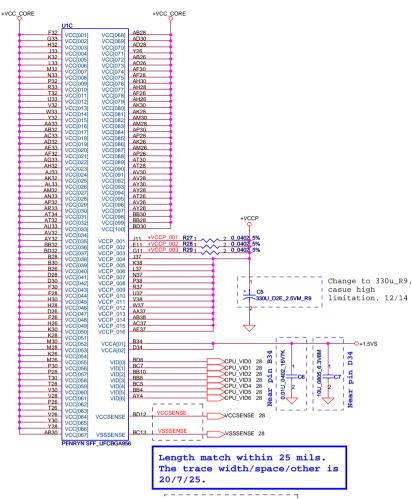
COMP[0,2] trace width is

18 mils. COMP[1,3] trace

layout note: Route TEST3 & TEST5 traces on ground referenced layer to the TPs

CPU_BSEL	CPU_BSEL2	CPU_BSEL1	CPU_BSEL0					
166	0	1	1					
200	0	1	0					
266	0	0	0					





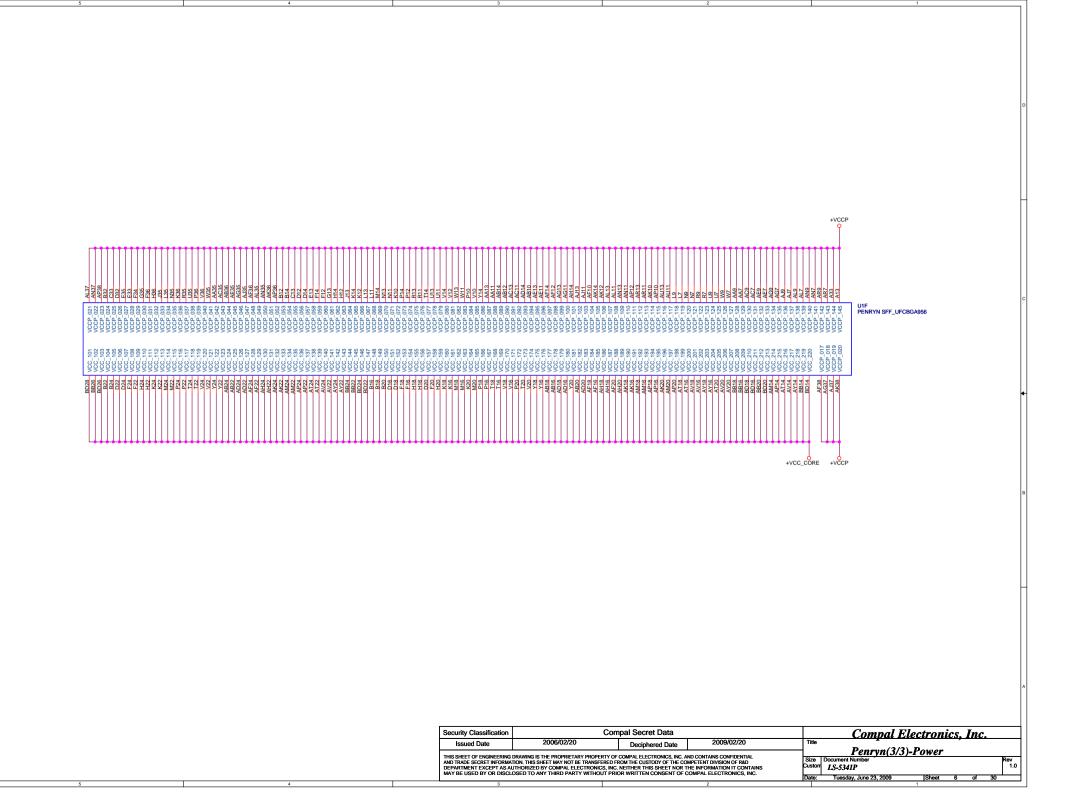
+VCC_CORE

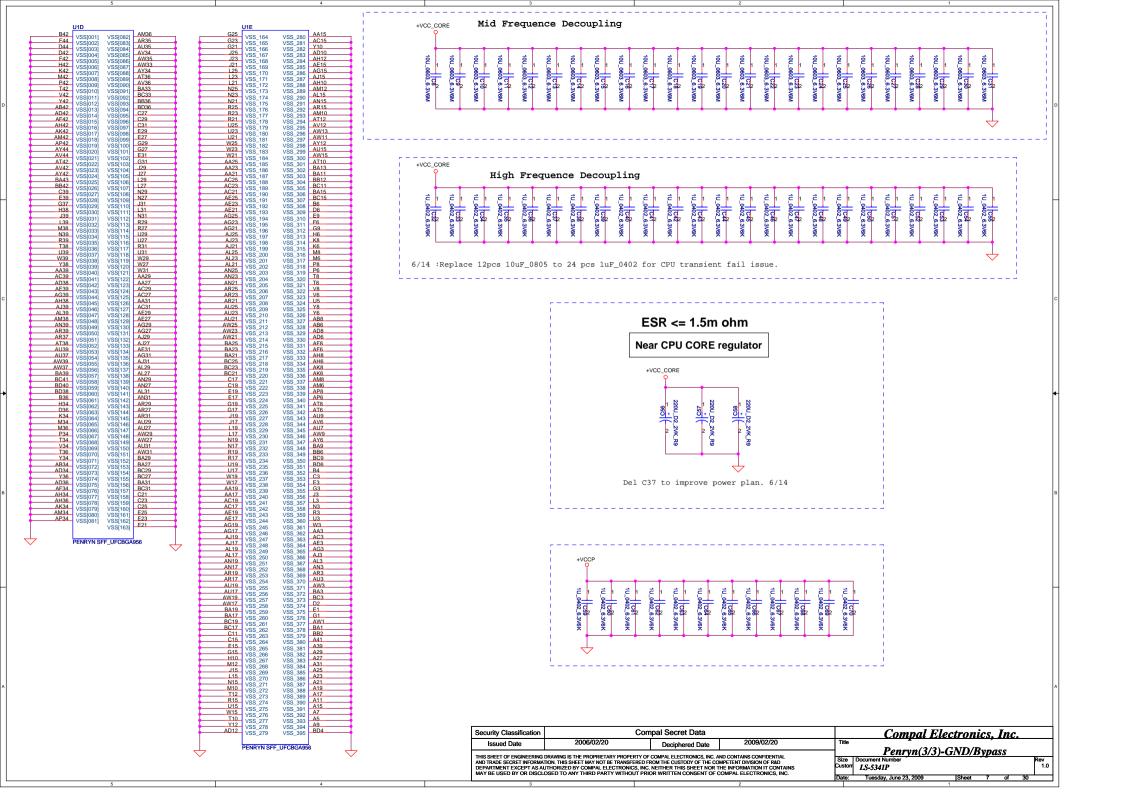
R34
100/0402_1%

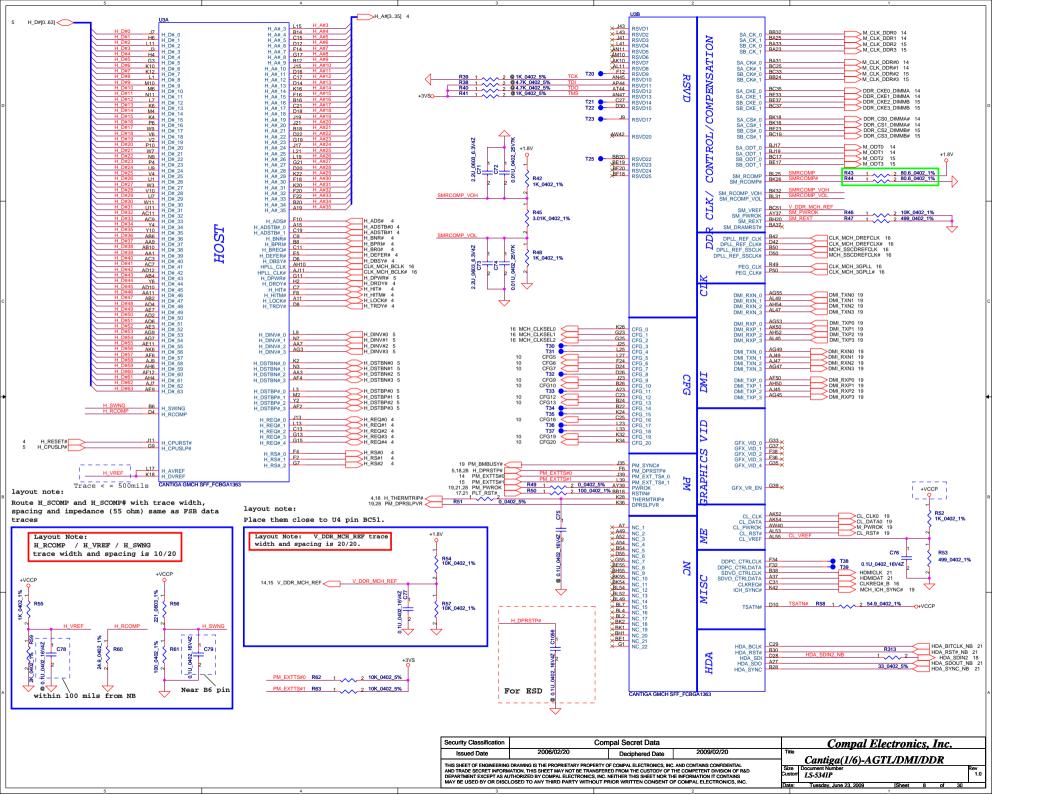
R35
2 VSSSENSE

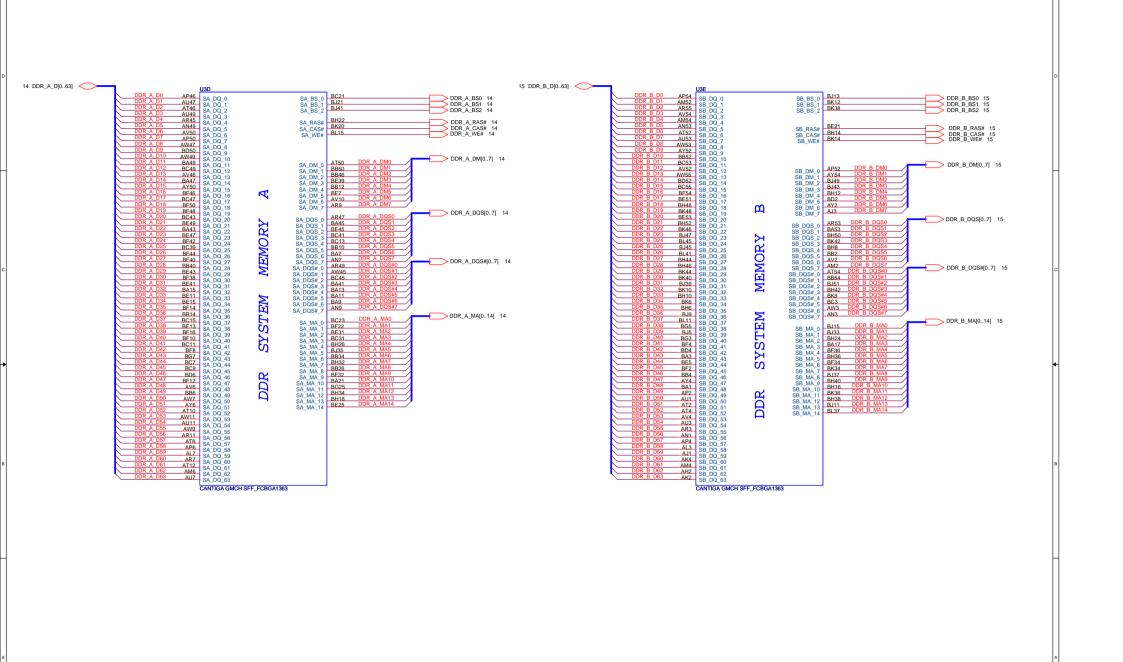
100/0402_1%

Close to CPU pin
within 500mils.

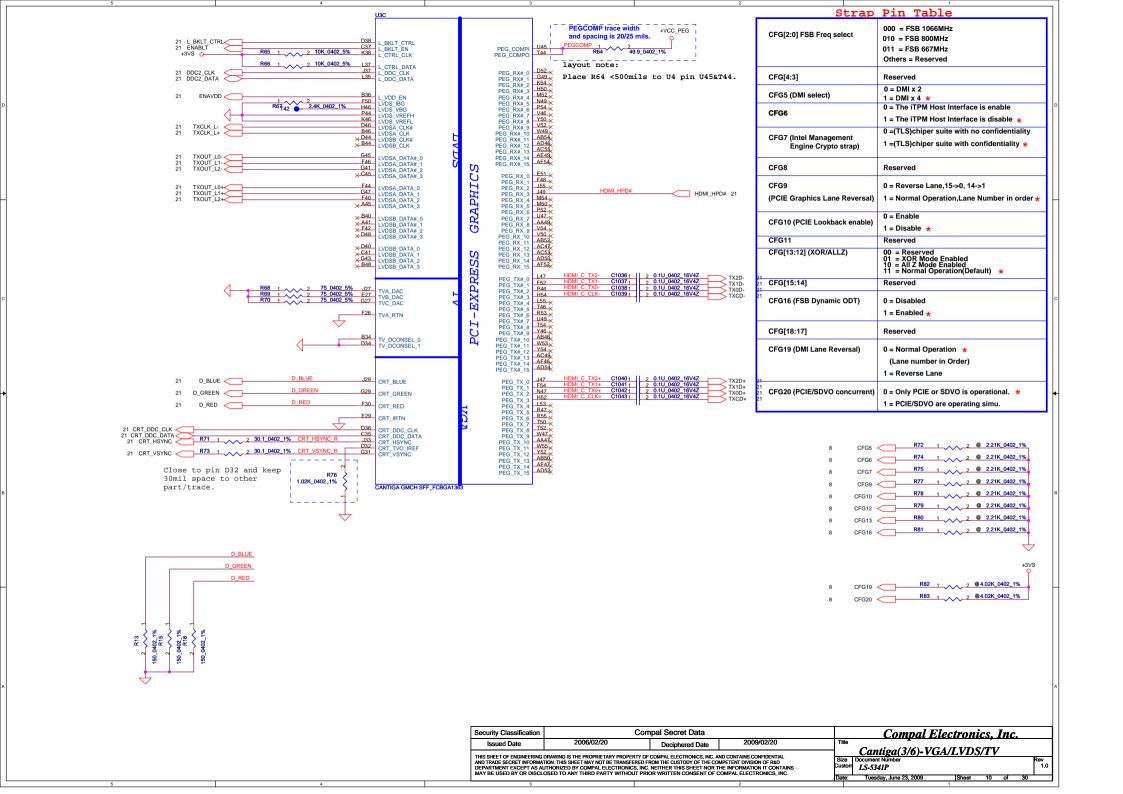


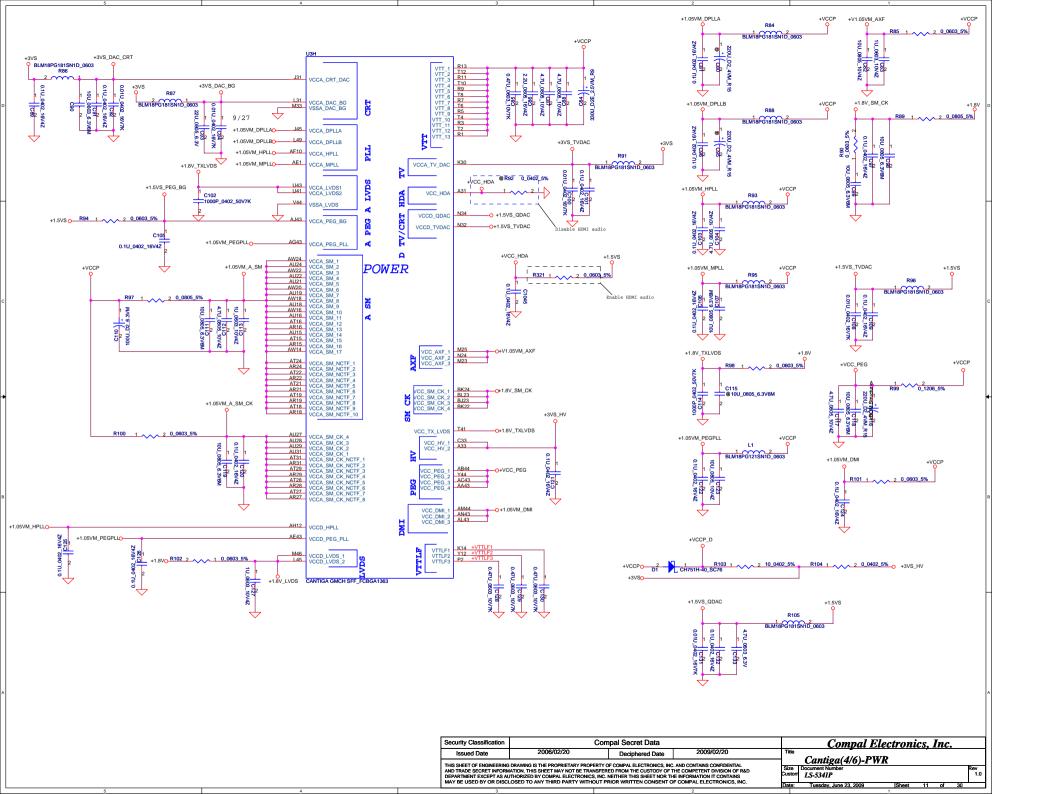


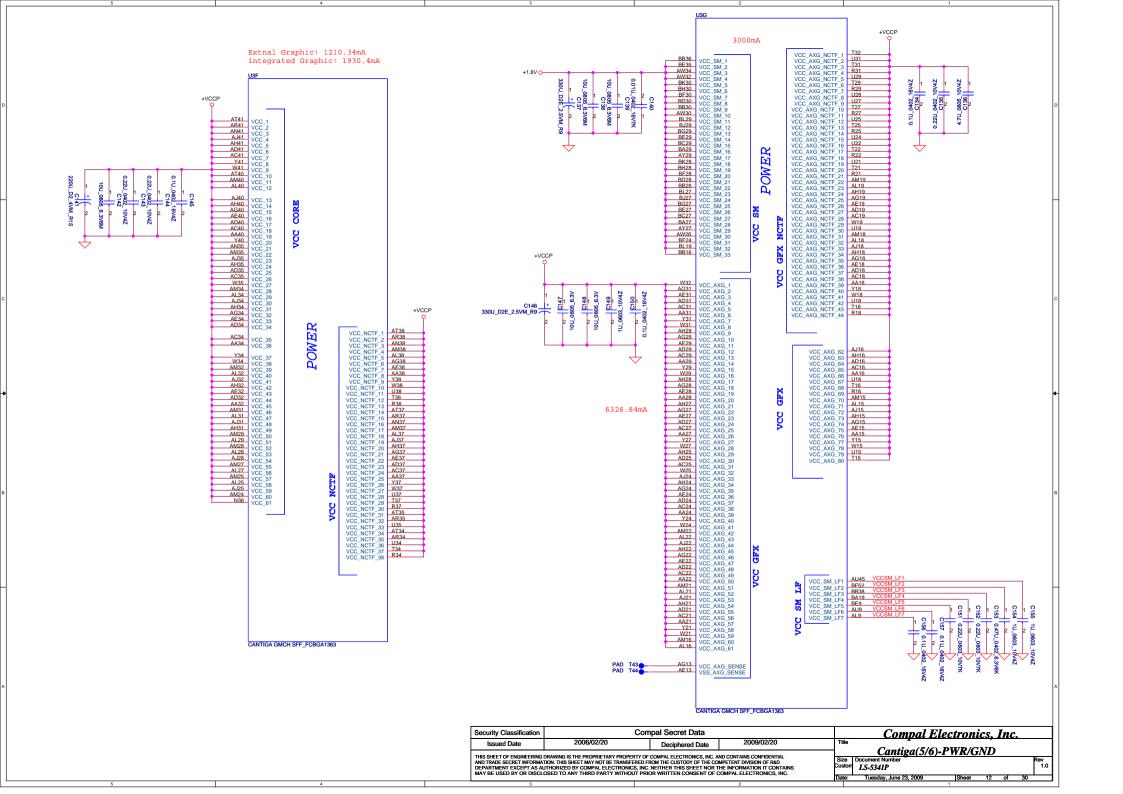


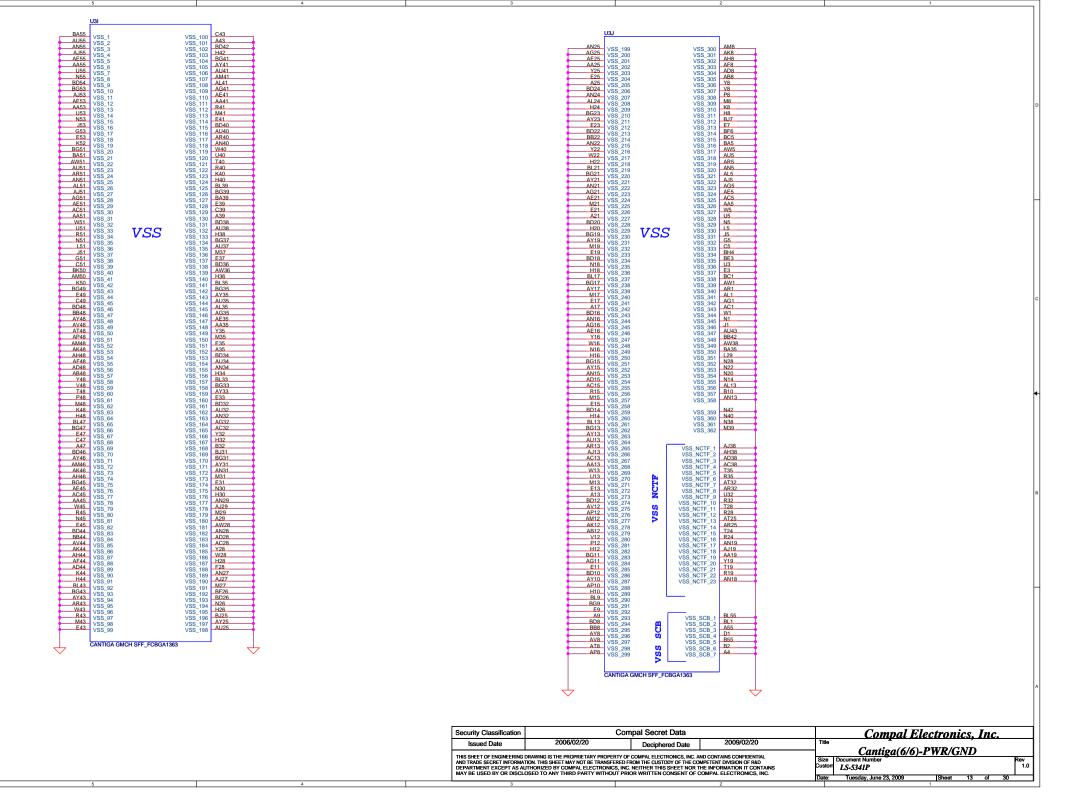


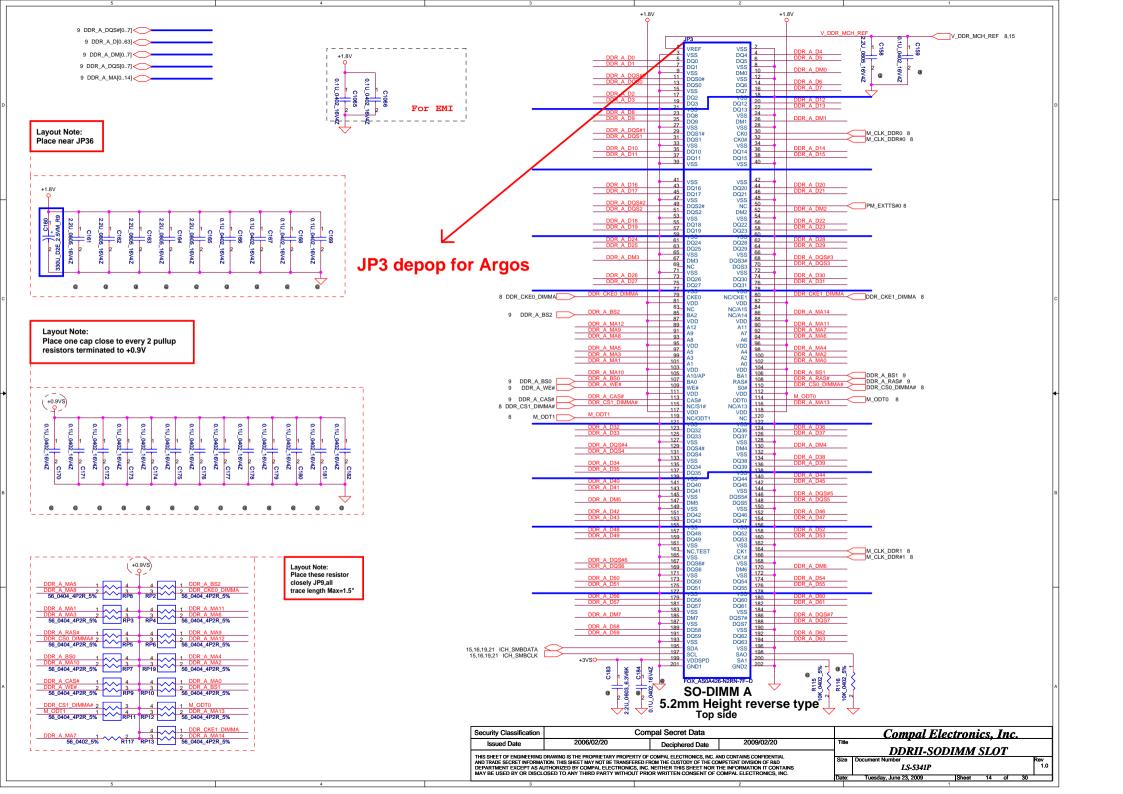
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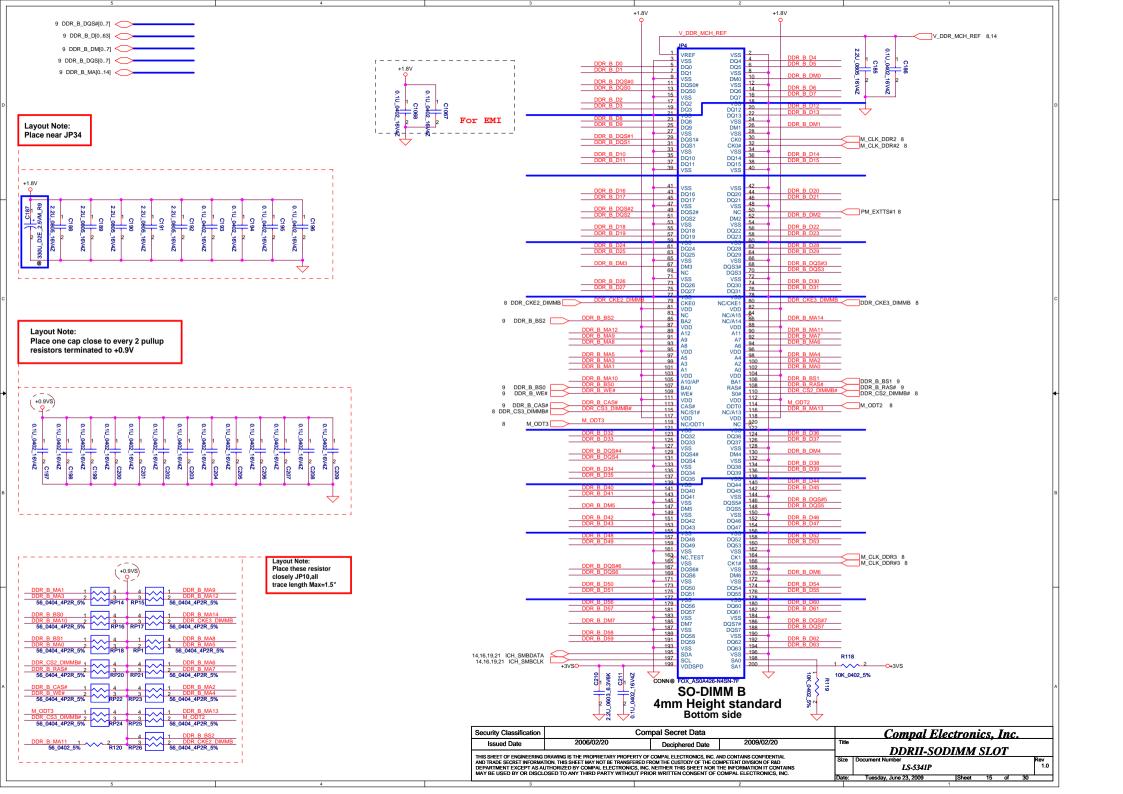


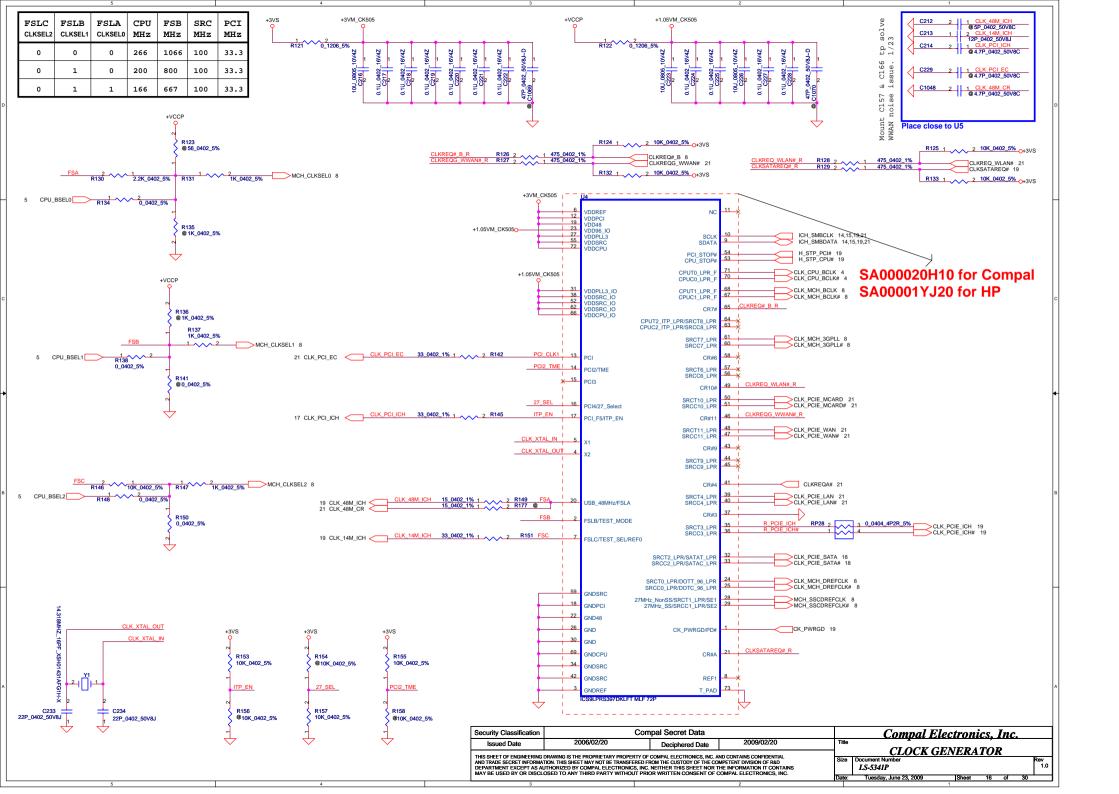


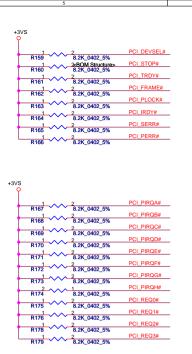


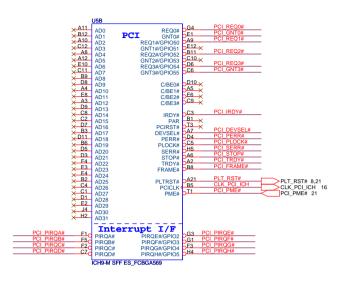


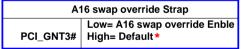












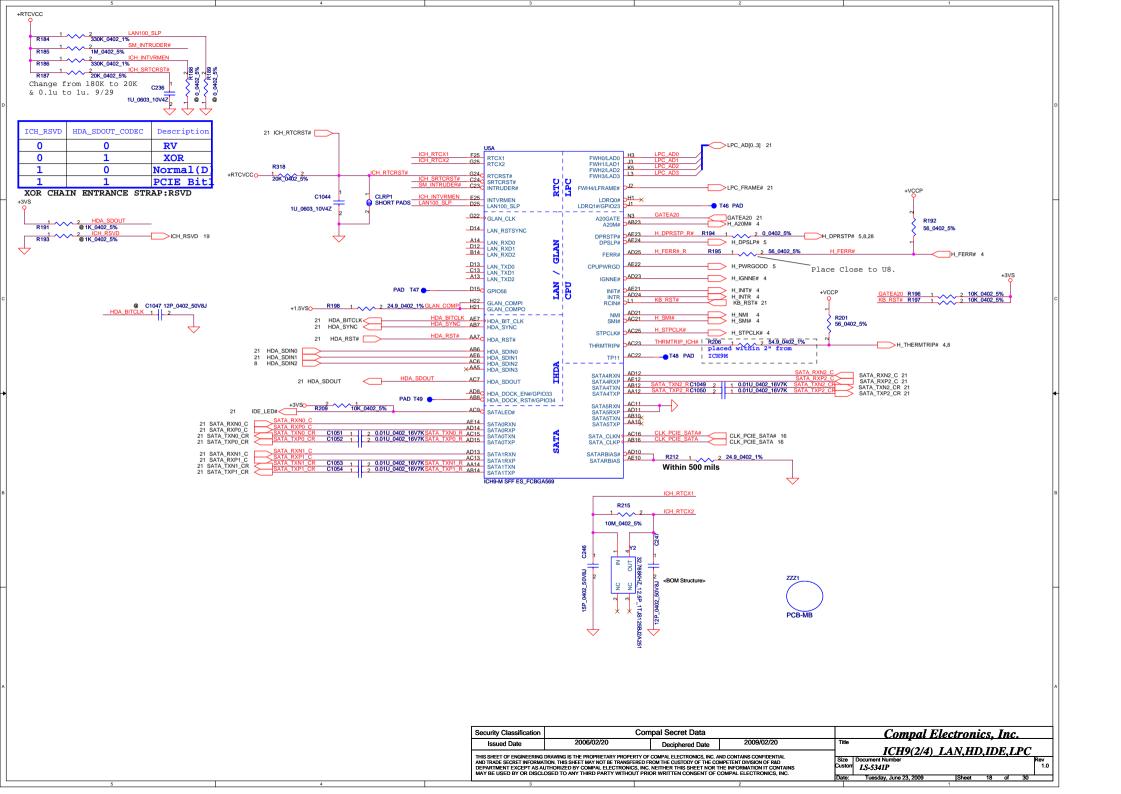


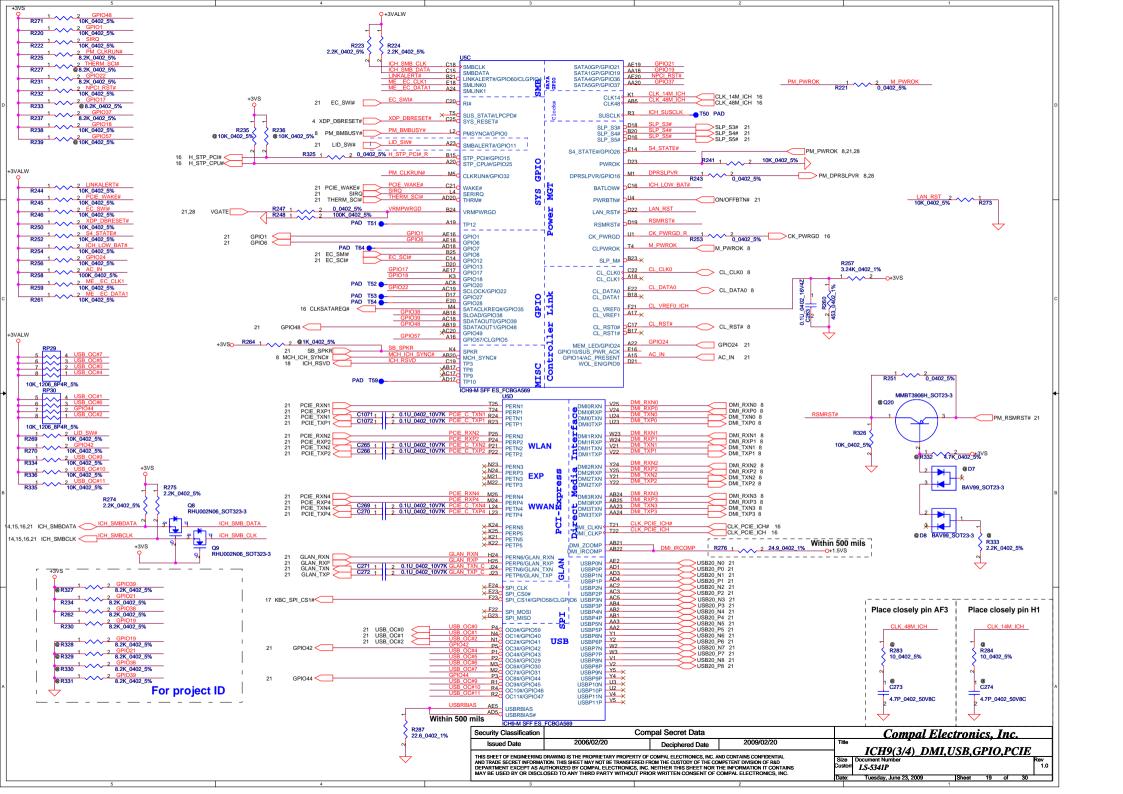
Boot BIOS S		
PCI_GNT0#	SPI_CS#1	Boot BIOS Location
0	1	SPI
1	0	PCI
1	1	LPC *

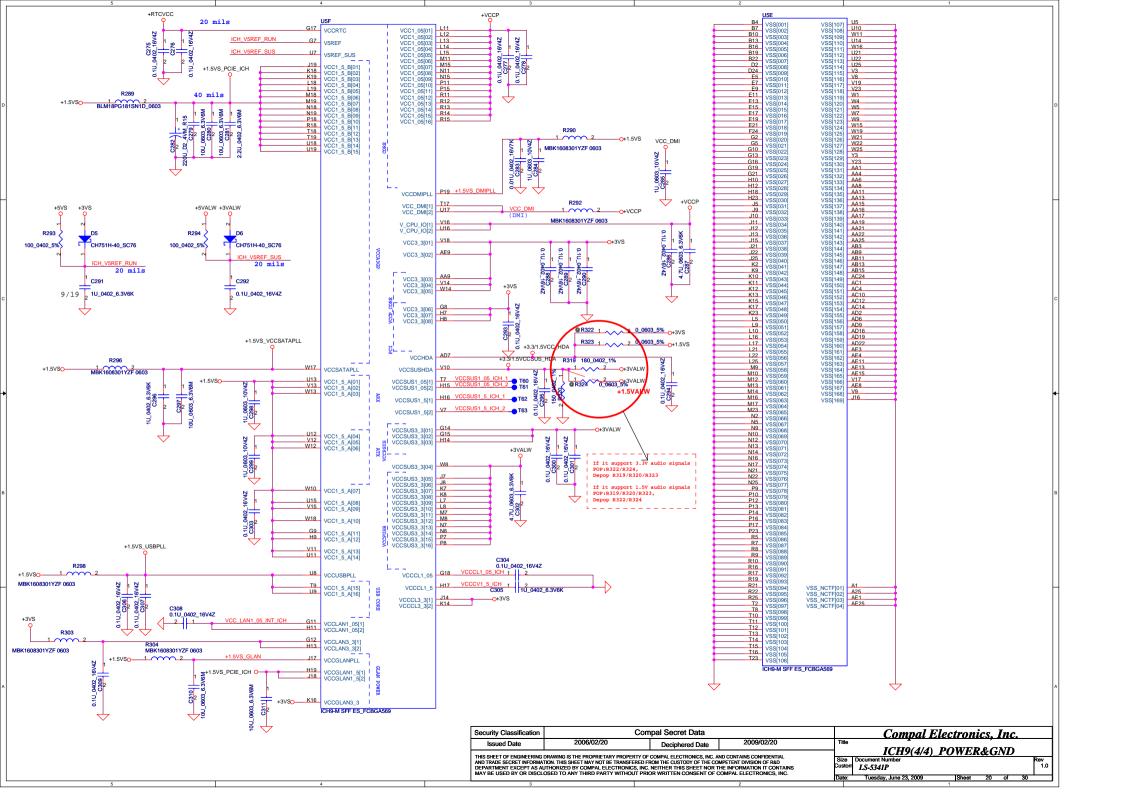


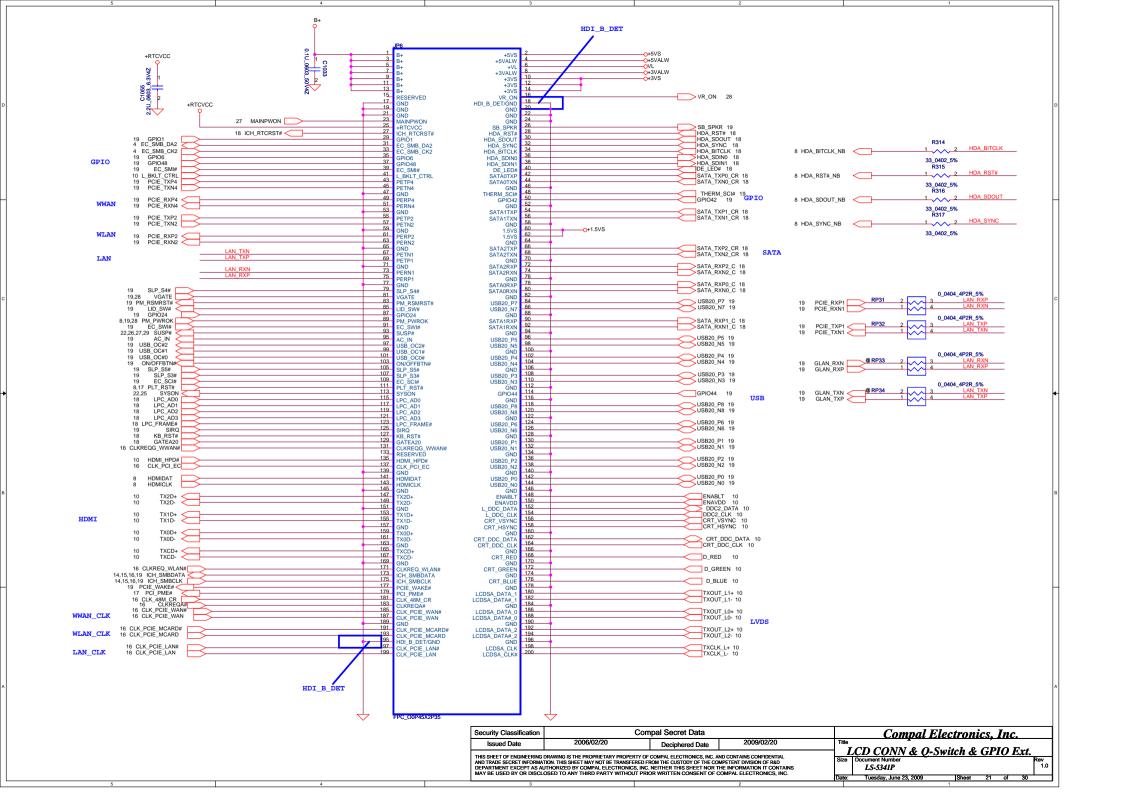


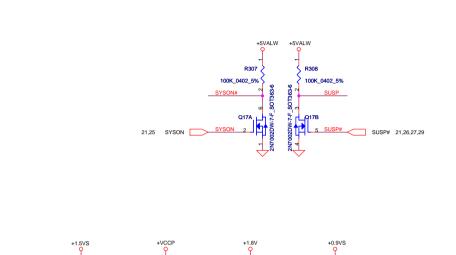
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470_0402_5%

Q19A

470_0402_5%

Q18A

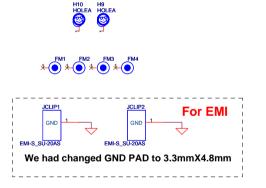
470_0402_5%

Q18B

R312

Q19B

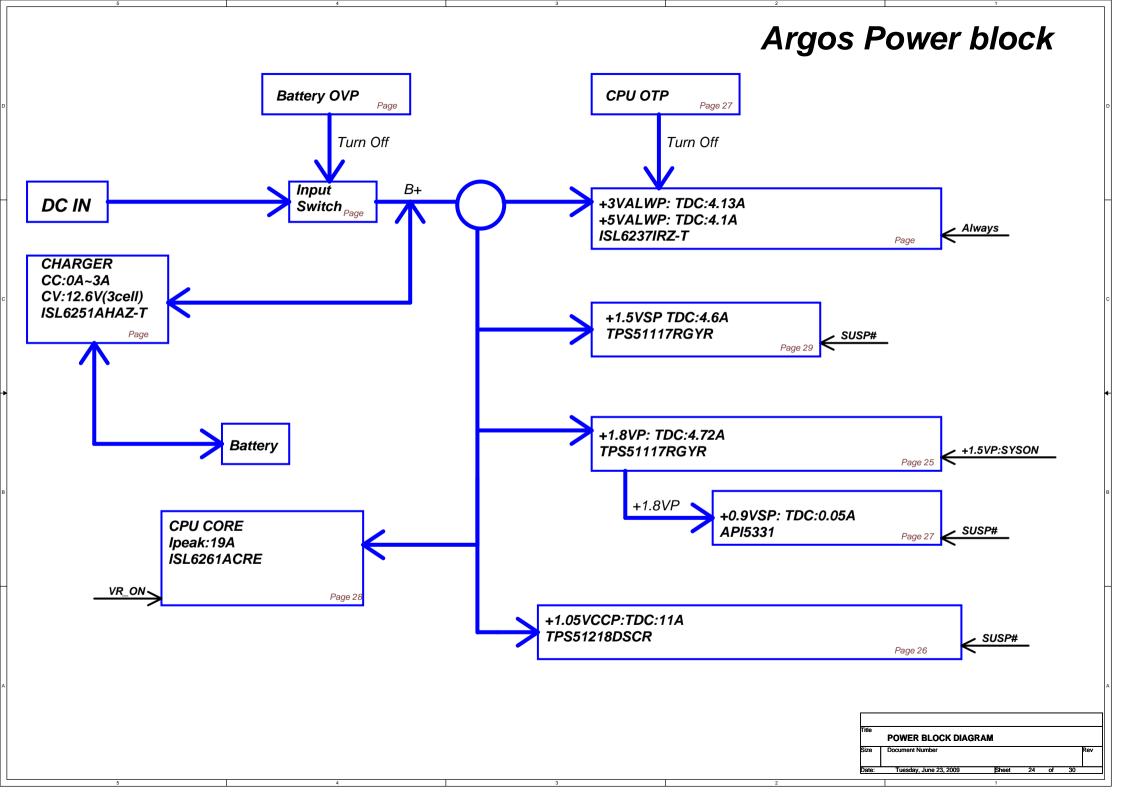
470_0402_5%

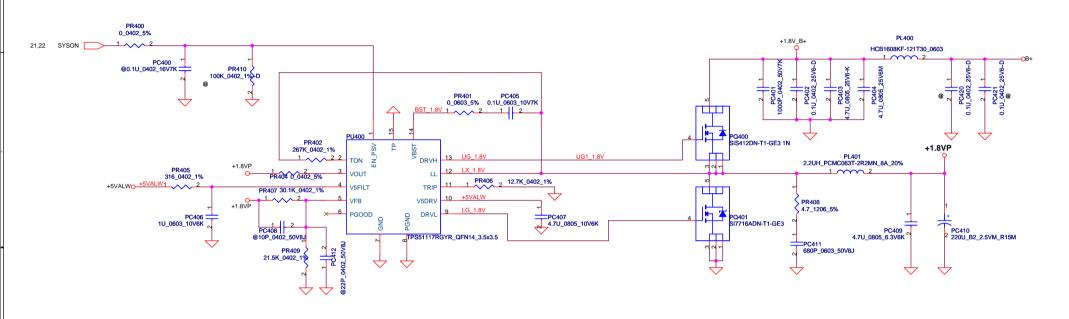




Ve	rsion change list (P.I.R. List)	EE section	n Page 1 of 1		
Item	Reason for change	PG#	Modify List	Date	Phase
1	Reserve support to HDMI audio	11	Add R321 and C1045	2009/03/13	Rev02
2	Follow Intel DG CAP size	7	Change C8~C23 from 0805 to 0603 C59~C70 from 0603 to 0402	2009/03/13	Rev02
3	Reserve EMI solution	4	Add C1046	2009/03/19	Rev02
4	Reserve RF solution	18	Add C1047,C1048	2009/03/19	Rev02
5	Modify layout routing on DDR signals to meet Intel DG	14,15	JP3 modify to SP07F00176L (5.2mm reverse type) JP4 modify to SP07000BR00 (4mm standard type)	2009/03/20	Rev02
6	Reserve support to 3.3V/1.5V audio signals	20	Add R322,R323 and R324	2009/03/23	Rev02
7	Follow Intel DG on SATA signals routing	18	Delete R210,R211,R213,R214,R216,R217,Add C1049~C1054	2009/03/23	Rev02
8	Reserve one CAP for RTC power	21	Add C1055	2009/03/25	Rev02
9	Reserve CAP for EMI	4,8	Add C1056~C1064	2009/03/25	Rev02
10	Reserve CAP for EMI	14,15	Add C1065~C1068	2009/03/26	Rev02
11	Follow Intel check list(REV2.1)	10	Change R67 to 2.4K ohm	2009/03/26	Rev02
12	Fix power derating for +VCC_PEG	11	Change R99 package from 0805 to 1206	2009/03/27	Rev02
13	Support Intel DPST function except GS40	10	Add L_BKLT_CTRL signal	2009/03/27	Rev02
14	Follow Intel recommend	8	Change R53 to 499 ohm	2009/04/23	Rev03
15	Remove CL_REF1 circuit w/o iAMT	19	Delete R265,R266 and C264	2009/04/23	Rev03
16	Reserve 0 ohm on PCI_STP# signal for seligo CLKGEN issue	19	Add R325 and delete R240	2009/04/23	Rev03
17	Add Intel resume reset circuit	19	Add Q20,R332,R333,D7 and D8 and change R251 to 0 ohm	2009/04/23	Rev03
18	Reserve Project ID	19	Add R327~R330	2009/04/23	Rev03
19	Modify EC_SCI# on GPIO for SW recommend	19	EC_SCI# change from GPIO7 to 12 and delete R263	2009/04/23	Rev03
20	Follow vendor recommend	16	Change R149 and R177 to 15ohm	2009/04/23	Rev03
21	Follow RF team recommend	16	Add C1069 and C1070	2009/04/23	Rev03
22	For Battery life on PCle port	19	Reserve LOM PCle signals between Port6 and Port1and add C1071,C1072,R337~R344	2009/04/27	Rev03
23	For Intel PCICLK routing buffer	16	Modify CLK_PCI_EC from PCICLK3 to PCICLK1	2009/04/27	Rev03
24	Fix USB initial when system boot	19	Add R334~R336	2009/05/05	Rev03
25	Fix crystal EA report	16,18	Change Y1 to SJ100003B00,C233,C234 to 22P and C246 to 15P	2009/05/05	Rev03
26	Reserve EMI solution for XDP	4	Add D9~D12 and delete C1058~C1064	2009/05/05	Rev03
27	For layout routing	21	R337~R344 change to RP31~RP34	2009/05/12	Rev03
28	For Intel DG	4,17,19	R10 change to depop,R172>8.2K,R250>10K,R230>8.2K	2009/05/12	Rev03
29	For EMI recommend	16	R177 change to depop	2009/05/12	Rev03
30	For EMI recommend	14,15,22	Add JCLIP1 and JCLIP2 ,Pop C1065~C1068	2009/06/16	Rev1.0
31	For delete TP location to fix Intel recommend VCCP power rail	8	Del T12~T15,T16~T18 and T24,T26~T27	2009/06/16	Rev1.0
32	For Argos project cost down	14	Depop C158~C159,C161~C184	2009/06/16	Rev1.0

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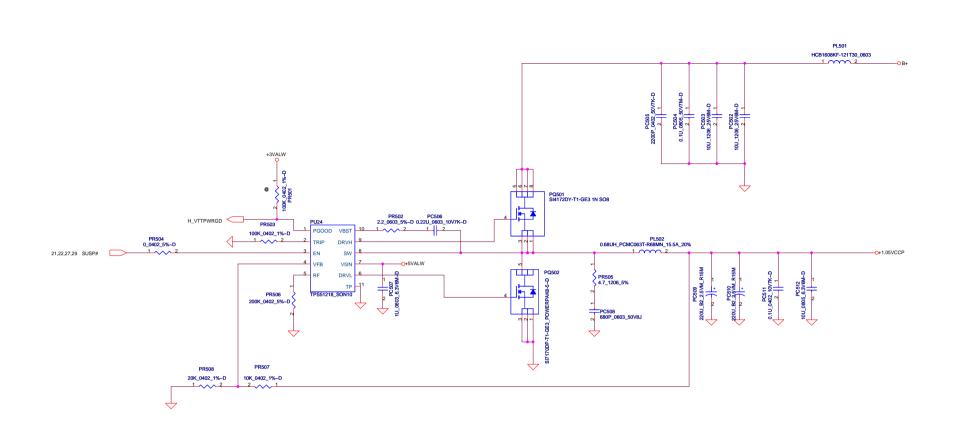




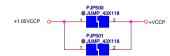
+1.8VP imax=5.4 A ; ipeak=6.746A Rds(on)=13.5m (Typ) ; 16.5m (Max) iocp=8A F=300Hz



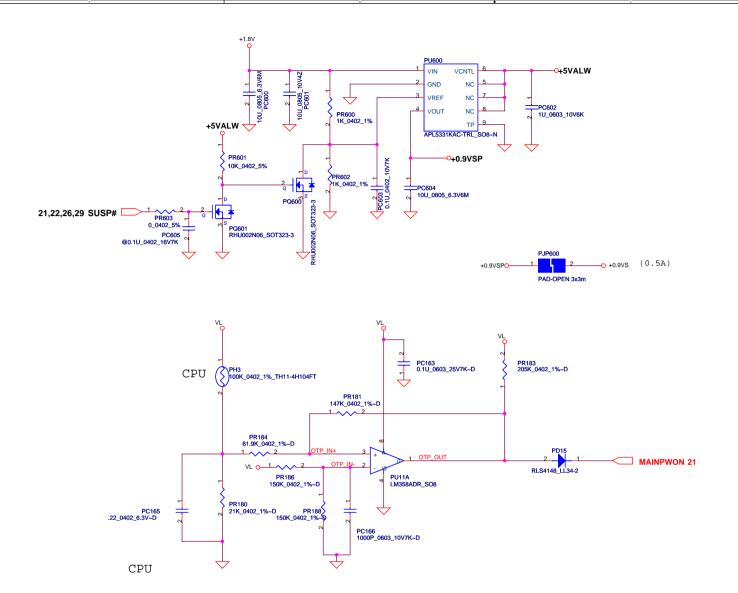
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+1.05VCCP imax=12.32A ipeak=17.6A Rds(on)=5.5m (Typ); 6.7m (Max) iocp=A F=350kHz

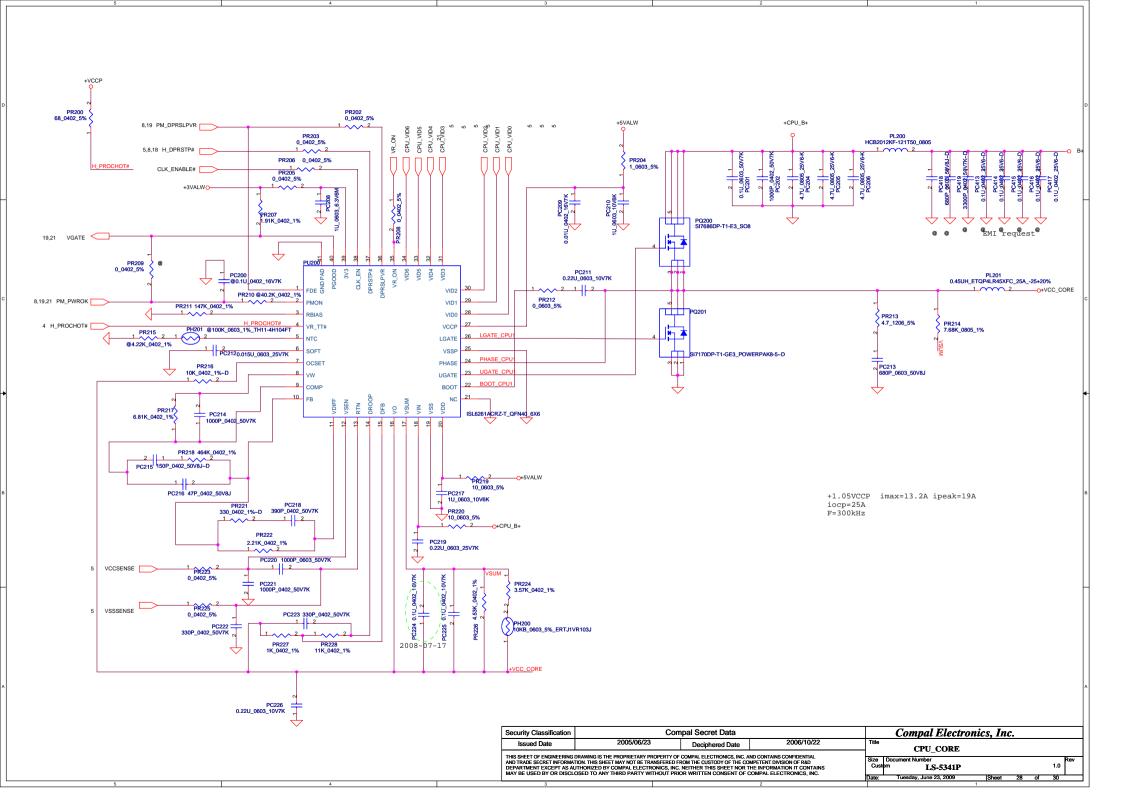


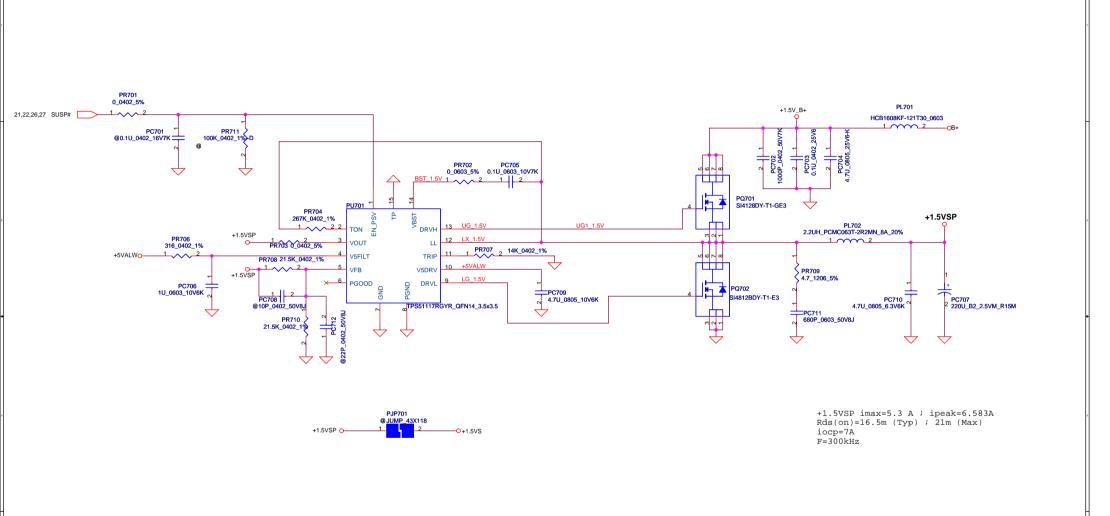
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				Date:	Tuesday, June 23, 2009	Sheet	26	of	30	



PH3 under CPU botten side : CPU thermal protection at 90 +-3 degree C Recovery at 50 +-3 degree C

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Vers	ion change list (P.I.R. List)	power section	Page 1 of 1		
Item	Reason for change	PG#	Modify List	Date	Phase
01	slove power on hard on DC mode	P27	change PC165 from 1000P to 0.22u PC166 from lu to 1000P	06/22/09	X-build
02	slove power on hard on DC mode	P17	change PR68 from 100k to 0 ohm	06/22/09	X-build
03	Add AC-IN margin for Temp/Volt test	P15	change PR194 from 19.6k to 20.5k	06/22/09	X-build
04	Add AC-IN margin for Temp/Volt test	P15	change PU3 from BIT3021 to APL5156	06/22/09	X-build
05					
06					
07					
08					
09					
10					
ļ					
			Security Classification Compal Secret Data Issued Date 2005/03/10 Deciphered Date	2006/03/10	Title
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